

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.01286	100.0	0.26839
			Subtotal	0.01286	100	0.26839
Die	Doped silicon	Silicon (Si)	7440-21-3	0.07668	100.0	1.6
			Subtotal	0.07668	100	1.6
Solder Wire	Tin alloy	Tin (Sn)	7440-31-5	0.00772	10.0	0.161
	Silver alloy	Silver (Ag)	7440-22-4	0.00154	2.0	0.0322
	Lead alloy	Lead (Pb)	7439-92-1	0.0679	88.0	1.4168
			Subtotal	0.07716	100	1.61
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.1029	100.0	2.14708
			Subtotal	0.1029	100	2.14708
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.00704	0.03	0.14694
	Pure metal layer	Zinc (Zn)	7440-66-6	0.00469	0.02	0.09796
	Pure metal layer	Tin (Sn)	7440-31-5	0.00704	0.03	0.14694
	Pure metal layer	Iron (Fe)	7439-89-6	0.02582	0.11	0.53877
	Pure metal layer	Copper (Cu)	7440-50-8	23.42871	99.81	488.8594
			Subtotal	23.4733	100	489.79001
Post-plating	Pure metal	Tin (Sn)	7440-31-5	0.24763	100.0	5.167
			Subtotal	0.24763	100	5.167
Mould Compound	Polymer	Tetrabromobisphenol A/Epichlorohydrin polymer	40039-93-8	2.28028	3.0	47.58
	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	4.56057	6.0	95.16
	Polymer	Epichlorohydrin/o-Cresol/Formaldehyde polymer (generic)	29690-82-2	7.60095	10.0	158.6
	Carbon Black	Carbon black	1333-86-4	0.38005	0.5	7.93
	Filler	Misc. Silica compounds (generic)	14808-60-7	59.28738	78.0	1237.08
	Flame retardant	Antimony Trioxide (Sb2O3) - cas no. 1309-64-4	1309-64-4	1.90024	2.5	39.65
			Subtotal	76.00947	100	1586
			Total	100	100	2086.58248

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